The Most Accurate Atomic Force Microscope

Park NX-Wafer

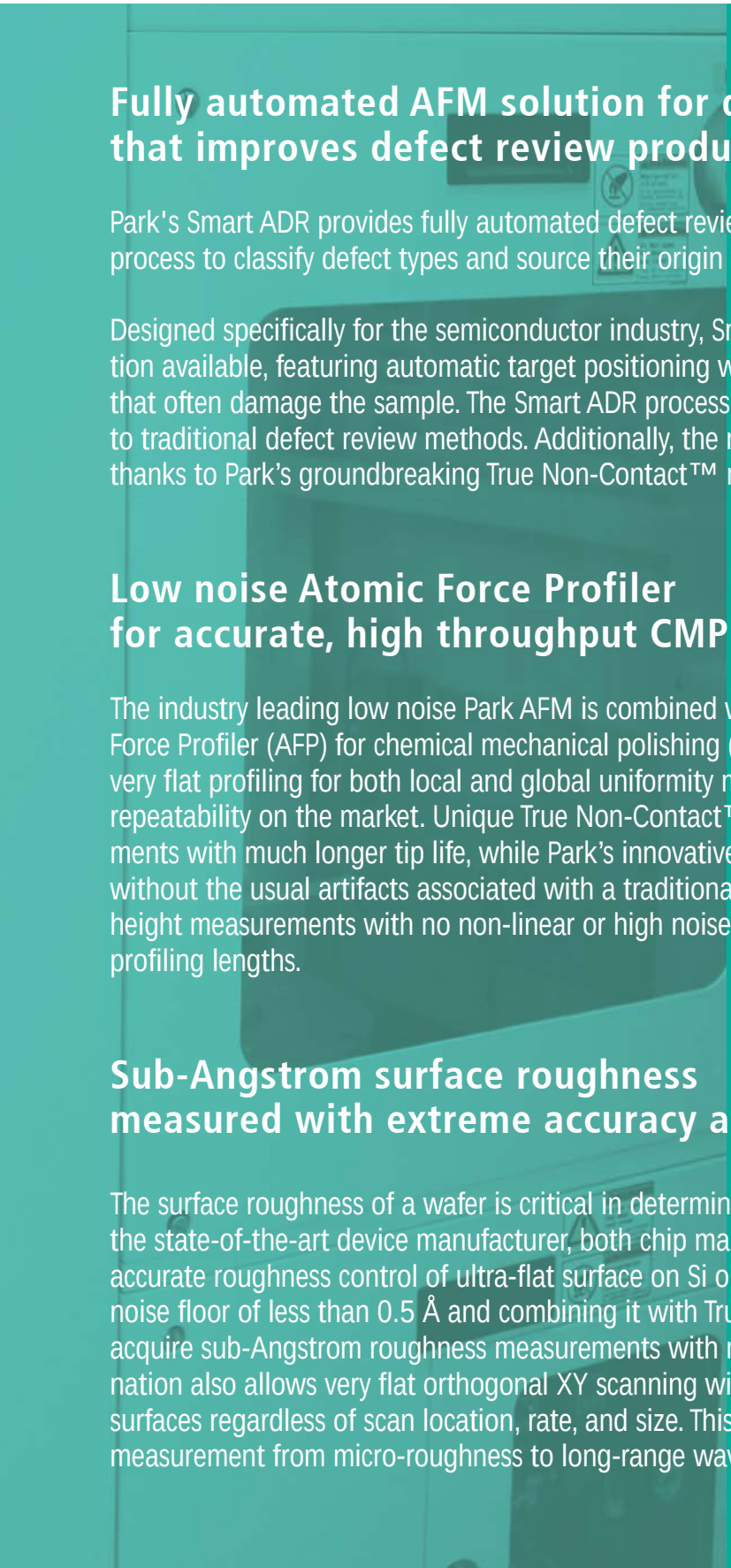
Low Noise, High Throughput Atomic Force Profiler with Automatic Defect Review

www.parkAFM.com

Park SYSTEMS

Park NX-WAFER

The only wafer fab AFM with automatic defect review



Fully automated AFM solution for defect imaging and analysis that improves defect review productivity by up to 1,000%.

Park's Smart ADR provides fully automated defect review and identification, enabling a critical inline process to classify defect types and source their origin through high resolution 3D imaging.

Designed specifically for the semiconductor industry, Smart ADR is the most advanced defect review solution available, featuring automatic target positioning without the need for labor intensive reference marks that often damage the sample. The Smart ADR process improves productivity by up to 1,000% compared to traditional defect review methods. Additionally, the new ADR capability offers up to 20x longer tip life thanks to Park's groundbreaking True Non-Contact™ mode AFM technology.

Low noise Atomic Force Profiler for accurate, high throughput CMP profile measurements

The industry leading low noise Park AFM is combined with a long range sliding stage to become an Atomic Force Profiler (AFP) for chemical mechanical polishing (CMP) metrology. The new low noise AFP provides very flat profiling for both local and global uniformity measurements with the best profiling accuracy and repeatability on the market. Unique True Non-Contact™ mode enables nondestructive in-line measurements with much longer tip life, while Park's innovative True Sample Topography™ obtains CMP profiles without the usual artifacts associated with a traditional piezotube-based AFP. This guarantees accurate height measurements with no non-linear or high noise background subtraction over a wide range of profiling lengths.

Sub-Angstrom surface roughness measured with extreme accuracy and minimized tip-to-tip variation

The surface roughness of a wafer is critical in determining the performance of a semiconductor device. For the state-of-the-art device manufacturer, both chip makers and wafer suppliers are demanding more accurate roughness control of ultra-flat surface on Si or SOI wafers. By delivering the industry's lowest noise floor of less than 0.5 Å and combining it with True Non-Contact™ mode, Park NX-Wafer can reliably acquire sub-Angstrom roughness measurements with minimum tip-to-tip variation. Park's Crosstalk Elimination also allows very flat orthogonal XY scanning with no background curvature, even on the flattest of surfaces regardless of scan location, rate, and size. This enables very accurate and repeatable surface measurement from micro-roughness to long-range waviness.


NX-Wafer
Atomic Force Microscope

Park NX-Wafer

High productivity and powerful features for inline wafer-fab metrology

Full Automation of High Throughput Defect Imaging

- Direct linkage to defect mapping inspection tools without stage calibration
- Automatic coordinate translation and alignment of defect maps through enhanced vision
- Automated zoom-in AFM scan of specified defects
- Automated analysis of imaged defect types

Low Noise, High Throughput Atomic Force Profiler

- CMP profiling up to 50 mm with long range traveling stage
- Industry leading sample topography repeatability measured by low noise Z detector
- Accurate surface height recording, even during high-speed profiling
- Superior tool-to-tool matching

Accurate Sub-Angstrom Surface Roughness Control

- Industry's lowest noise floor of less than 0.5 Å rms throughout the entire wafer area
- Immunity from parameter-dependent results with True Non-Contact™ mode
- Preserving the sharpness of the tip end for surface roughness accuracy
- 10x - 20x longer tip life than any other AFM

High-Throughput Wafer-Fab Inspection and Analysis

- Automatic tip exchange with 99.9% success rate and minimum tact time
- Equipment Front End Module (EFEM) for automatic wafer handling
- Cleanroom compatibility and remote control interface
- Automatic data acquisition and analysis of trench width, depth, and angle measurements

Park NX-Wafer

Productivity meets Accuracy

Automatic Defect Review for Bare Wafers and Substrates

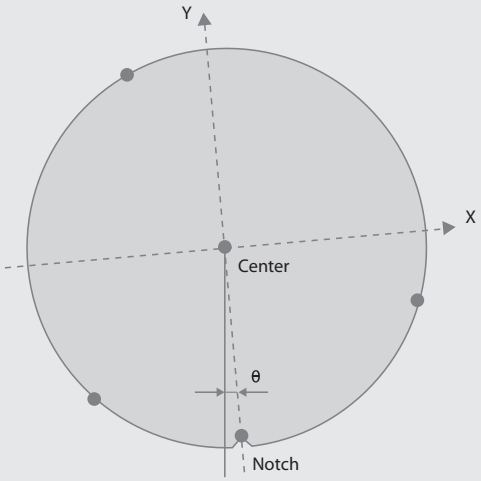
The new 300mm bare wafer ADR provides a fully automated defect review process from transfer and alignment of defect maps to the survey and zoom-in scan imaging of defects that uses a unique remapping process that does not require any reference marker on a sample wafer. Unlike SEM which leaves square-shaped destructive irradiation marks on defect sites after its run, the new Park ADR AFM enables advanced coordinate translation with enhanced vision that uses the wafer edge and notch to automatically enable linkage between a defect inspection tool and the AFM. Since it is fully automated, it does not require any separate steps to calibrate the stage of the targeted defect inspection system, increasing throughput by up to 1,000%.

Automatic Transfer and Alignment of Defect Maps with Enhanced Vision

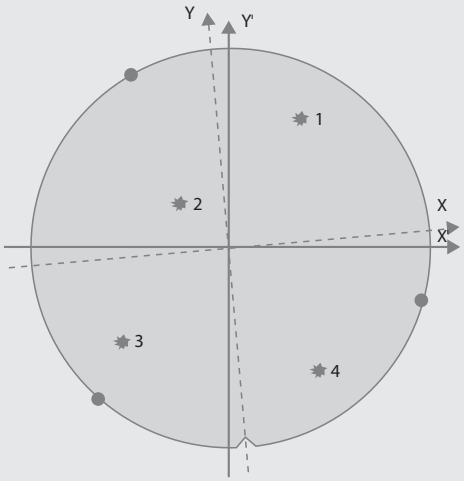
By utilizing Park's proprietary coordinate translation technique, the new Park ADR AFM can accurately transfer the defect maps obtained from a laser-scattering defect inspection tool to a 300 mm Park AFM system. This technology does not require any separate step to calibrate the stage of the targeted defect inspection system and allows full automation for high throughput defect imaging.

Coordinate Translation of Defect Maps to AFM by Enhanced Vision

Coarse alignment



Fine alignment

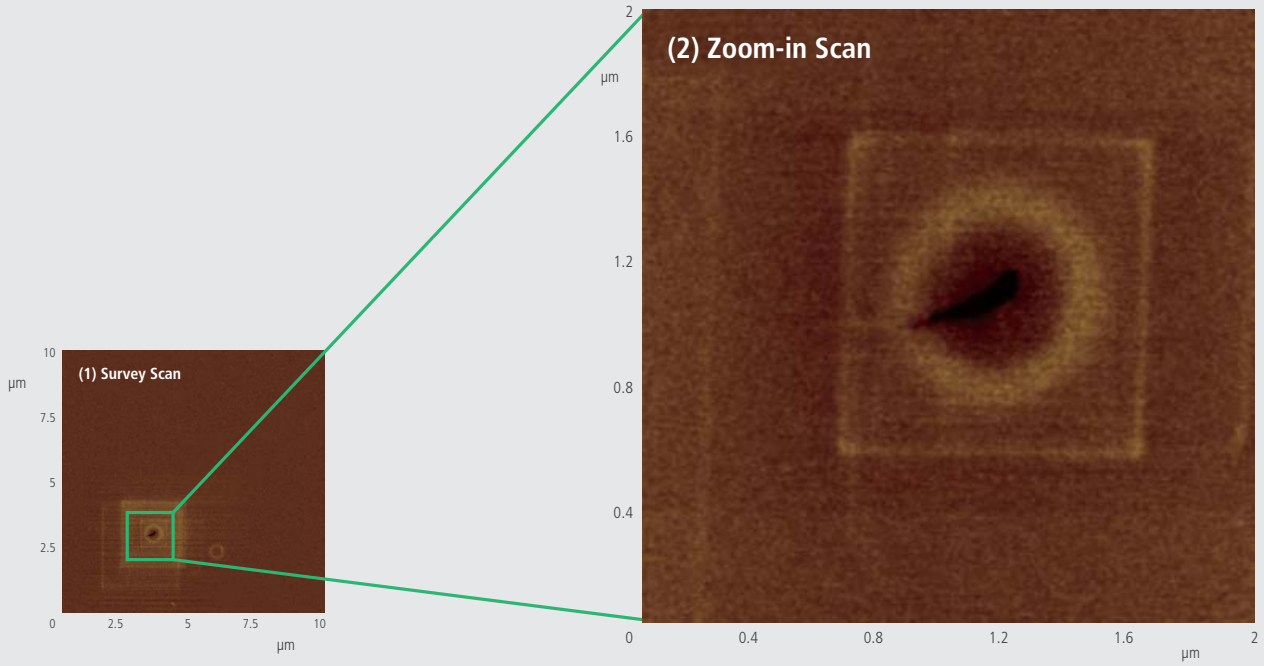


1. Wafer Center Position
2. Rotation Angle θ

Inspection Tool		ParkAFM
(X, Y)	→	(X', Y')
(X_1, Y_1)	→	(X'_1, Y'_1)
(X_2, Y_2)	→	(X'_2, Y'_2)
(X_3, Y_3)	→	(X'_3, Y'_3)
(X_4, Y_4)	→	(X'_4, Y'_4)

Automated Search & Zoom-in Scan

The defects are imaged in two steps; (1) a survey imaging, either by AFM or enhanced optical vision, to refine the defect location, then (2) a zoom-in AFM scan to obtain a detailed image of the defect, presenting automatic analysis of the defect type and the subsequent defect dimensions.



Long Range Profiling for CMP Characterization

Planarization is the most important step in the back-end processes where metals and dielectric materials are used. Both local and global uniformity after chemical mechanical polishing (CMP) affect the yield of chip manufacturing significantly. Accurate CMP profiling is a critical metrology necessary to optimize process conditions for best planarity and improve production yield.

Combining Park NX-Wafer with a sliding stage provides a long range profiling capability for CMP metrology. Due to the unique scanner design of Park's automated AFM, the combined system provides very flat profiling and there is no need for complex background subtraction or calibration after each measurement. The Park NX-Wafer enables unprecedented CMP metrology of both local and global planarity measurements including dishing, erosion, and edge-over-erosion (EOE).

Sub-Angstrom Surface Roughness Control

Semiconductor suppliers are developing ultra-flat wafers to address the ever-increasing need for shrinking device dimensions. However, there has never been a metrology tool capable of providing accurate and reliable measurements for the sub-Angstrom roughness of these substrate surfaces. By delivering the industry's lowest noise floor of less than 0.5 Å throughout the wafer area, and combining it with True Non-Contact™ mode, the Park NX-Wafer can make accurate, repeatable, and reproducible sub-Angstrom roughness measurements for the flattest substrates and wafers with minimized tip-to-tip variation. Very accurate and repeatable surface measurements can be obtained even for the long-range waviness measurement of scan sizes up to 100 µm x 100 µm.

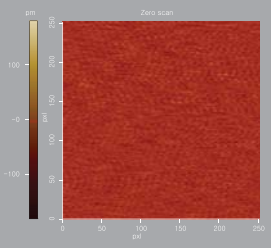
Park NX-Wafer

Powerful and yet reliable AFM

Industry's Lowest Noise Floor

To detect the smallest sample features, and image the flattest surfaces, Park has engineered the industry's lowest noise floor specification of < 0.5 Å. The noise floor data is determined using a "zero scan." The system noise is measured with the cantilever in contact with the sample surface at a single point under the following conditions:

- 0 nm x 0 nm scan, staying at one point.
- 0.5 gain in contact mode
- 256 x 256 pixels



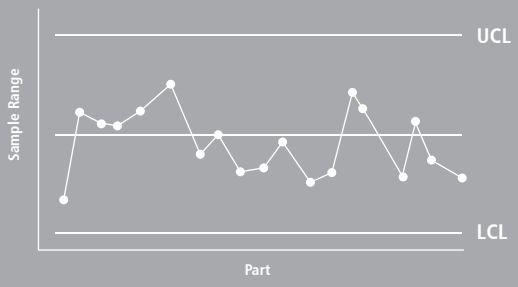
Typically 0.3 Å rms or lower

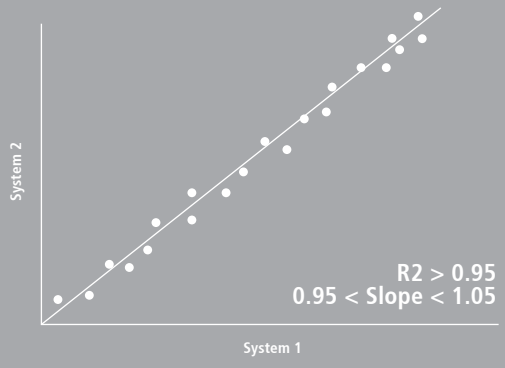
Statistics

Region	Mid(pm)	Mean(pm)	Rpv(pm)	Rq(pm)	Ra(pm)
Red	0.000	-0.011	359.496	30.025	19.177

Gauge Repeatability and Reproducibility

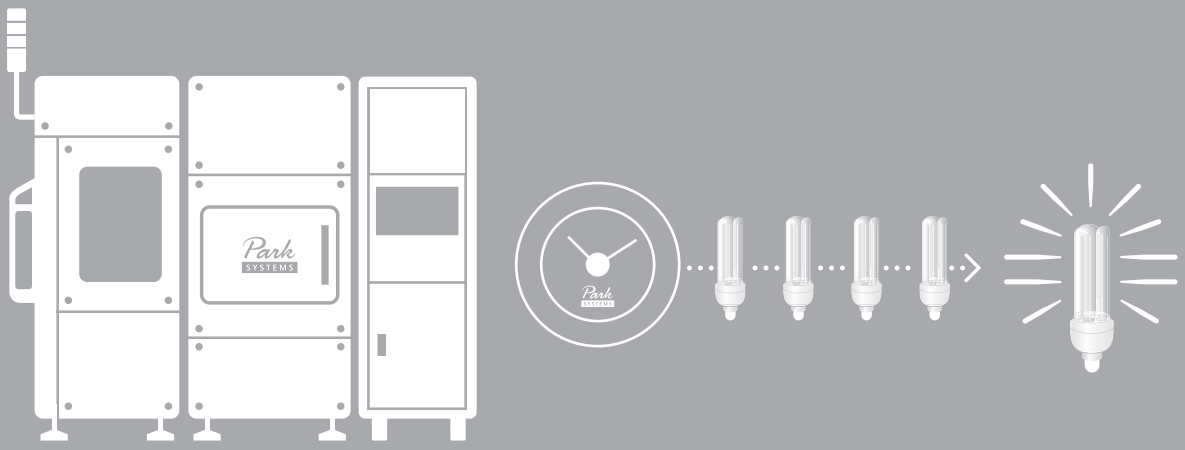
Due to the ever-decreasing size of components, manufacturers now require the highest level of quality control. Park AFM can provide 1 gauge sigma of less than 1 angstrom.





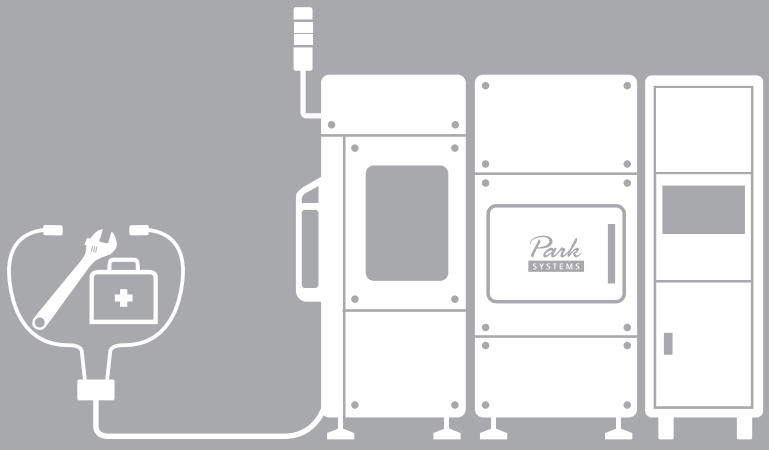
Tool-to-tool Correlation

Thanks to Park's revolutionary AFM platform designed for industrial metrology, Park NX-Wafer will correlate with any existing Park AFMs that have been previously used for manufacturing, inspection, analysis, or research.



System Uptime

Our engineers and scientists have adopted the most rigorous industry standard product development to ensure the highest level of system reliability. Park NX-Wafer can be incorporated seamlessly either as an inline or as an offline inspection tool, with minimal maintenance requirements.



Service and Maintenance

Park is committed to the highest level of service and support. We put every effort to understand our customers' needs. We place the highest priority in meeting promised delivery dates, guaranteed quality, and thorough after-sales service.

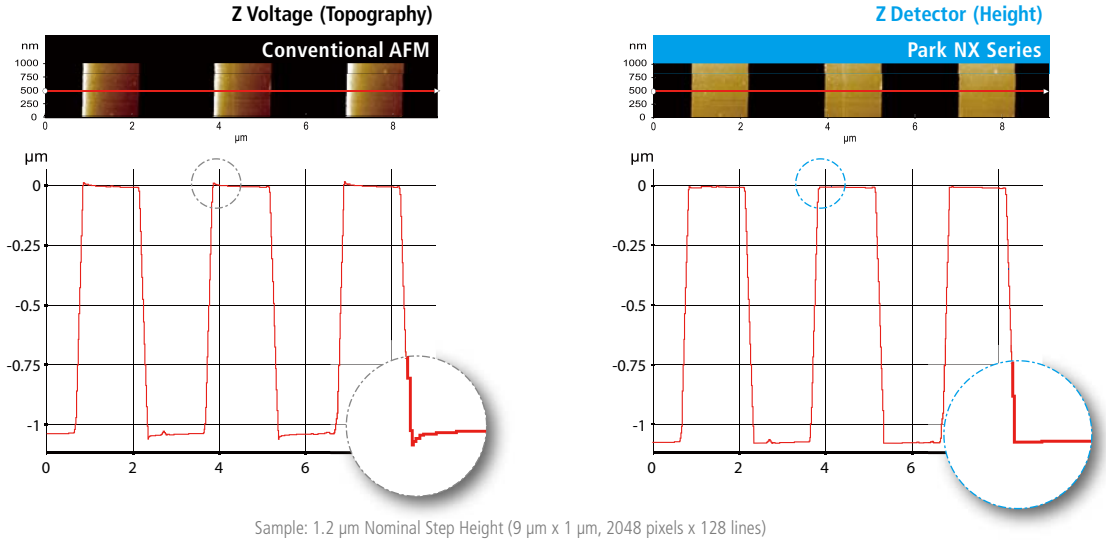
Park NX-Wafer

Park AFM technology

Industry Leading Low Noise Z Detector

Our AFMs are equipped with the most effective low noise Z detectors in the field, with a noise of 0.2 Å over large bandwidth. This produces highly accurate sample topography, no edge overshoot and no need for calibration. Just one of the many ways Park NX-Wafer saves you time and gives you better data.

Accurate Sample Topography Measured by Low Noise Z Detector

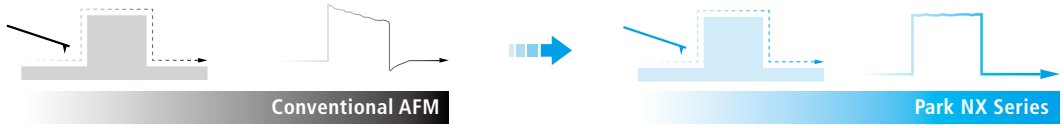


Sample: 1.2 µm Nominal Step Height (9 µm x 1 µm, 2048 pixels x 128 lines)

Piezoelectric creep effect

No creep effect

No artifact by AFM scanner in low noise closed-loop topography

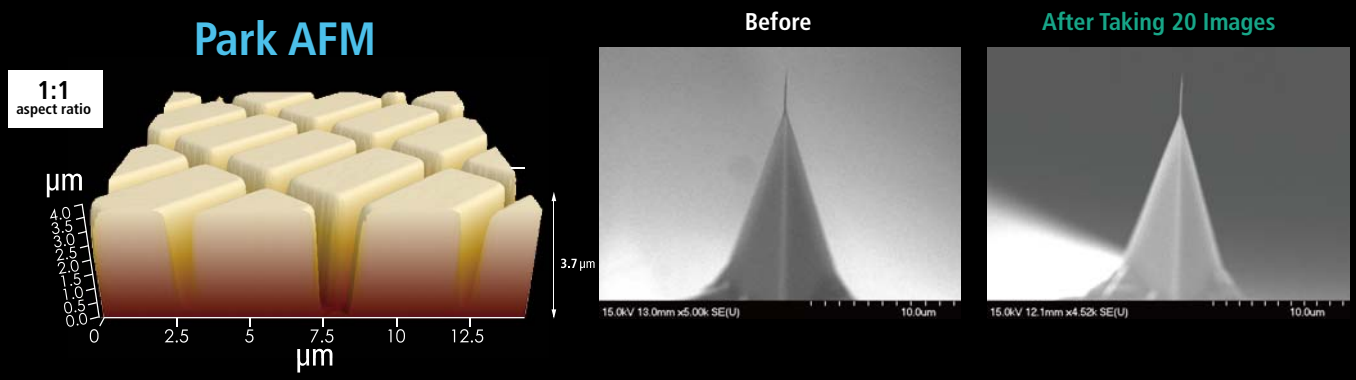


- Uses low noise Z detector signal for topography
- Has low Z detector noise of 0.02 nm over large bandwidth
- Has no edge overshoot at the leading and trailing edges
- Needs calibration done only once at the factory

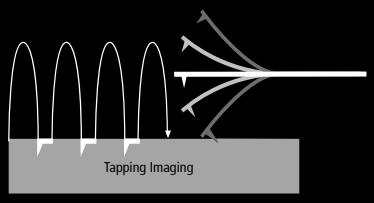
True Non-Contact™ Mode Preserves Sharp Tip

AFM tips are so brittle that touching a sample will instantly reduce the resolution and quality of the image they produce. For soft and delicate samples, the tip will also damage the sample and result in inaccurate sample height measurements, something that can cost you valuable time and money.

True Non-Contact™ mode, a scan mode unique to Park AFMs, consistently produces high resolution and accurate data while maintaining the integrity of the sample.



Accurate Feedback by Faster Z-servo enables True Non-Contact AFM



Tapping Imaging

- Quick tip wear = Blurred low-resolution scan
- Destructive tip-sample interaction = Sample damage and modification
- Highly parameter-dependent

True Non-Contact™ Mode

- Less tip wear = Prolonged high-resolution scan
- Non-destructive tip-sample interaction = Minimized sample modification
- Immunity from parameter dependent results

Park NX-Wafer

The most innovative AFM technology in one powerful package

50mm Long Range Profiler

The long range profiler is an essential component of Atomic Force Profilometry (AFP) and comes with a dedicated user interface for the automated CMP profiling and analysis.

- Maximum sliding range: up to 50mm
- Out-of-Plane Motion (OPM): less than ± 10 nm @ 10 mm range
- Max number of data points: up to 1,048,576

100 μm x 100 μm Flexure-Guided XY Scanner with Closed-loop Dual Servo System

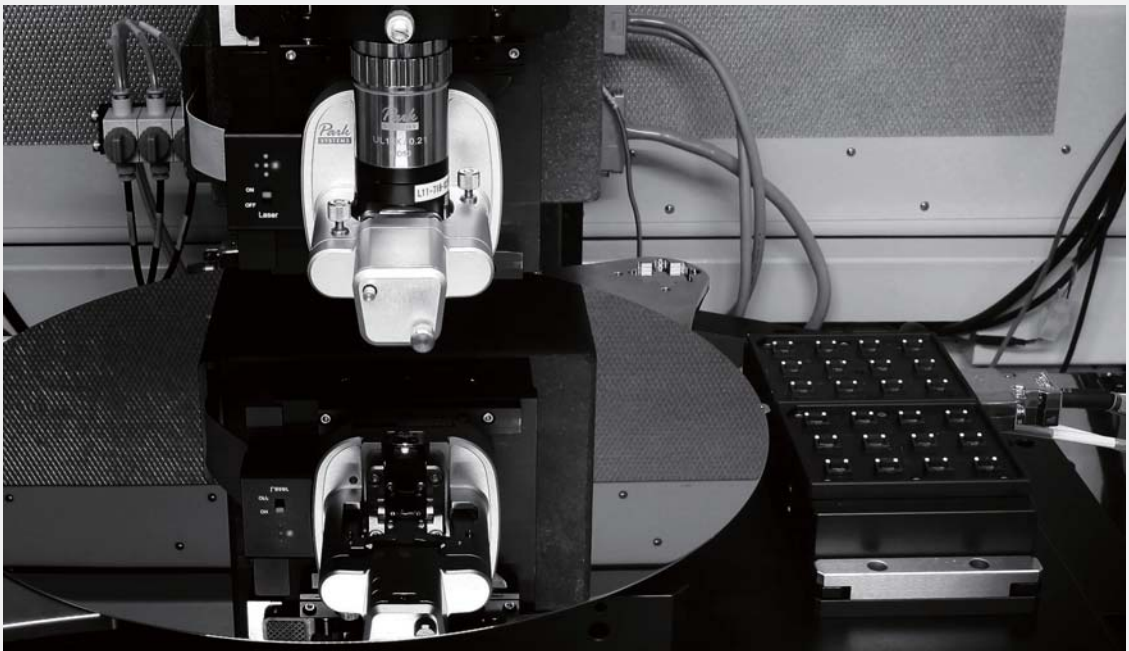
The XY scanner consists of symmetrical 2-dimensional flexure and high-force piezoelectric stacks that provide highly orthogonal movement with minimal out-of-plane motion, as well as the high responsiveness essential for precise sample scanning at the nanometer scale. Two symmetric, low-noise position sensors are incorporated on each axis of the XY scanner to retain a high level of scan orthagonality for the largest scan ranges and sample sizes. The secondary sensor corrects and compensates for non-linear and non-planar positional errors caused by a single sensor alone.

15 μm High Speed Z Scanner with Low Noise Position Sensor

The NX-Wafer provides you with unprecedented accuracy in topography height measurement by utilizing its ultra-low noise Z detector instead of the commonly used Z voltage signal that is non-linear in nature. This industry leading low noise Z detector replaces the applied Z voltage as the topography signal. Driven by a high-force piezoelectric stack and guided by a flexure structure, the standard Z scanner has a high resonant frequency of more than 9 kHz and Z-servo speed of more than 48 mm/sec tip velocity enabling more accurate feedback. The maximum Z scan range can be extended from 15 μm to 40 μm with the optional long range Z scanner.

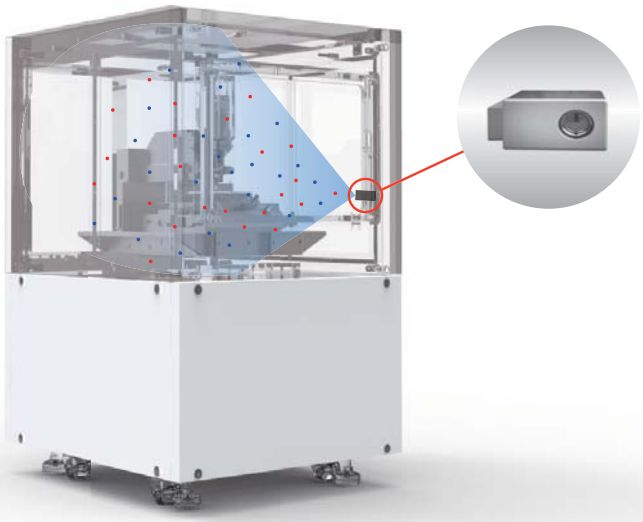
Automatic Tip Exchanger (ATX)

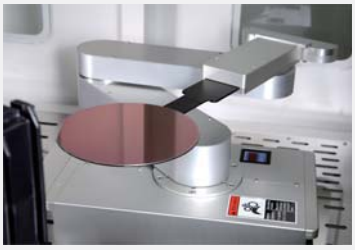
The ATX automatically locates tips by pattern recognition and uses a novel magnetic approach to disengage a used tip and pick up a new tip, with an incredible 99.9% success rate. The laser spot is then automatically optimized along the X- and Y-axis by motorized positioning knobs.



Ionization System for a more stable scanning environment

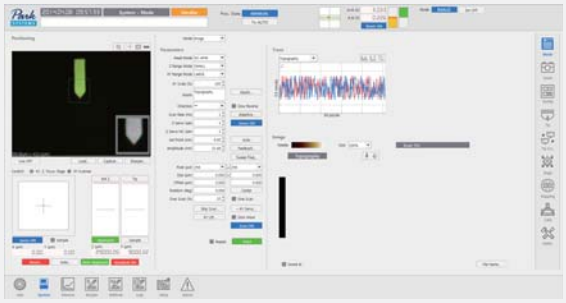
Our innovative ionization system quickly and effectively removes electrostatic charges in your sample's environment. Since the system always generates and maintains the ideal balance of positive and negative ions, it can create an extremely stable charge environment with little contamination of the surrounding area and minimal risk of accidental electrostatic charge during sample handling.





Automatic Wafer Handler (EFEM or FOUP)

The NX-Wafer can be configured for various automatic wafer handlers (EFEM or FOUP or other). The high-precision, nondestructive wafer handler robot arm fully ensures users always get fast and reliable wafer measurements.



Automatic Measurement Control so you can get accurate scans with less work

The NX-Wafer is equipped with automated software that makes operation nearly effortless. Just select the desired measurement program to get precise multi-site analysis with optimized settings for cantilever tuning, scan rate, gain, and set point parameters.

Park's user-friendly software interface gives you the flexibility to create customized operation routines so you can access the full power of the NX-Wafer and get the measurements you need.

Creating new routines is easy. It takes about 10 minutes to make one from scratch, or less than 5 minutes to modify an existing one.

Park NX-Wafer's automated system features:

- Auto, semi-auto, and manual mode so you have complete control
- Editable measurement method for each automated routine
- Live monitoring of the measurement process
- Automatic analysis of acquired measurement data

Park NX-Wafer
Specification

System Specification

200 mm Motorized XY stage

travels up to 275 mm × 200 mm, 0.5 µm resolution

300 mm Motorized XY stage:

travels up to 400 mm × 300 mm, 0.5 µm resolution
< 1 µm repeatability

Scanner Performances

XY Scanner

Single-module flexure XY scanner with closed-loop control
100 µm × 100 µm (large mode)
50 µm x 50 µm (medium mode)
10 µm × 10 µm (small mode)

XY Scanner Resolution

0.28 nm (large mode)
0.03 nm (small mode)

Dimension & Weight

200 mm System

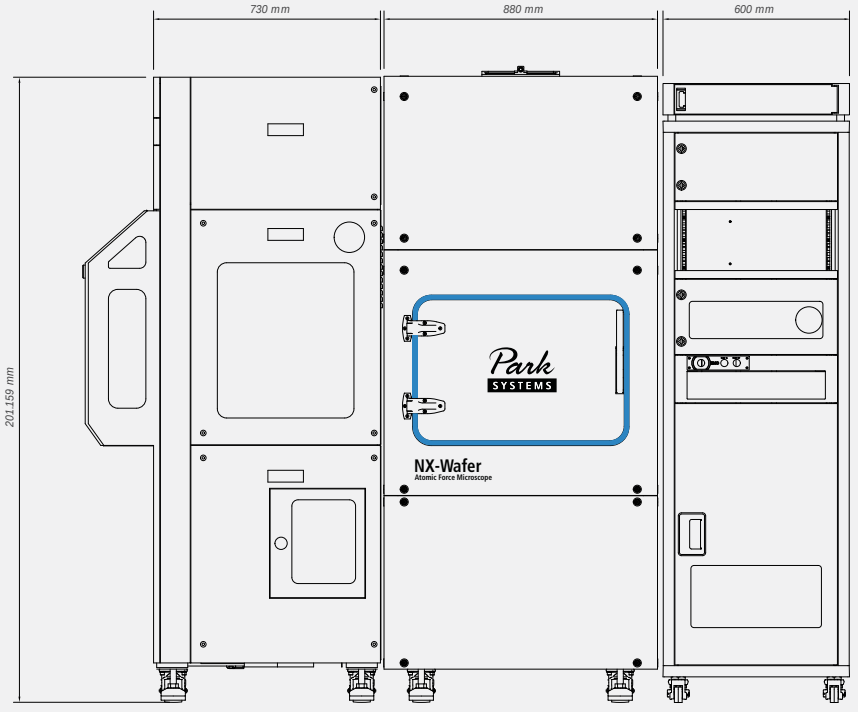
1480 mm (w) x 980 mm (d) x 2024 mm (h)
w/o EFEM, 750 kg approx. (incl. Control Cabinet)
2420 mm (w) x 1000 mm (d) x 2024 mm (h)
w/ EFEM, 1230 kg approx. (incl. Control Cabinet)

Ceiling Height:
2000 mm or more
Operator Working Space:
3300 mm (w) x 1950 mm (d), minimum

300 mm System

1820 mm (w) x 1170 mm (d) x 2024 mm (h)
w/o EFEM, 1320 kg approx. (incl. Control Cabinet)
3170 mm (w) x 1170 mm (d) x 2024 mm (h)
w/ EFEM, 1670 kg approx. (incl. Control Cabinet)

Ceiling Height:
2000 mm or more
Operator Working Space:
4500 mm (w) x 3120 mm (d)



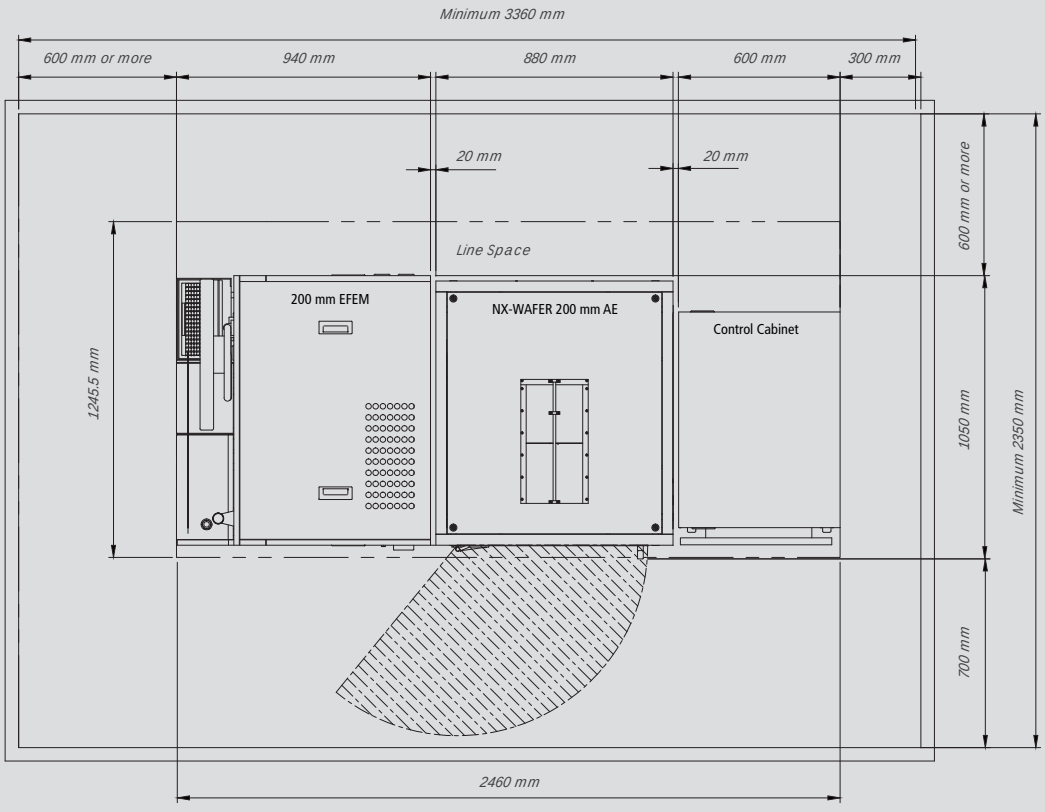
Motorized Z Stage	Motorized Focus Stage	Sample Thickness Allowance	Full scan range Z run-out	COGNEX Pattern Recognition
27 mm Z travel distance 0.08 µm resolution < 1 µm repeatability	9 mm Z travel distance for on-axis optics	Up to 20 mm	< 2 nm, repeatability < 1 nm	pattern align resolution of 1/4 pixel

Z Scanner Range	Z Scanner Resolution	Z Scanner Noise Floor	Z Scanner Detector Noise
15 µm (large mode) 2 µm (small mode)	0.016 nm (large mode) 0.002 nm (small mode)	< 0.05 nm	0.02 nm @ 1kHz

Facility Requirements

Room Temperature (Stand By)	Room Temperature (Operating)	Humidity	Floor Vibration Level
10 °C ~ 40 °C	18 °C ~ 24 °C	30% to 60% (not condensing)	VC-E (3 µm/sec)

Acoustic Noise	Pneumatics	Power Supply Rating	Total Power Consumption	Ground Resistance
Below 65 dB	Vacuum: -80 kPa CDA (or N_2): 0.7 MPa	208 V ~ 240 V, single phase, 15 A (max)	2 KW (typical)	Below 100 ohms



Park Systems

Dedicated to producing the most accurate and easiest to use AFMs

The global headquarters is located at
Korean Advanced Nanotechnology Center (KANC) in Suwon, Korea.

More than a quarter century ago, the foundations for Park Systems were laid at Stanford University where Dr. Sang-il Park, the founder of Park Systems worked as an integral part of the group that first developed AFM technology. After perfecting the technology, he then went on to create the first commercial AFM and later Park Systems was born.

Park Systems strives everyday to live up to the innovative spirit of its beginnings. Throughout our long history, we have honored our commitment to providing the most accurate and yet very easy to use AFMs, with revolutionary features like True Non-Contact™ mode, and many automated software tools. We are not simply content to rest on our past success. All of our products are designed with same care and creativity that went into our first, allowing you to focus on getting results without worrying about the integrity of your tools.